## SKD8810R 20V N-Channel MOSFET

### **■ FEATURES**

20V/7A

 $RDS(ON) < 20m\Omega@VGS=4.5V$ 

RDS(ON) <  $24m\Omega$ @ VGS=2.5V

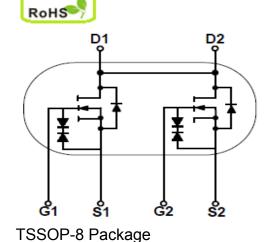
RDS(ON) <  $32m\Omega$ @ VGS=1.8V

ESD Rating: 2000V HBM

- High Cell Desity
- Lead free and Green Device Available
- Application
- Battery pack protection

## **■ PIN DESCRIPTION**





**Absolute Maximum Ratings** (T<sub>A</sub>=25°C unless otherwise noted)

| Symbol            | Parameter                            | Maximum              | Unit    |    |
|-------------------|--------------------------------------|----------------------|---------|----|
| $V_{DSS}$         | Drain-to-Source Voltage              |                      | 20      | V  |
| $V_{GSS}$         | Gate-to-Source Voltage               | ±12                  | V       |    |
| I <sub>D</sub>    | Continuous Drain Current             | T <sub>C</sub> =25°C | 7       | Α  |
|                   |                                      | T <sub>C</sub> =70°C | 5.5     | Α  |
| I <sub>DP</sub>   | Pulsed Drain Current                 | T <sub>C</sub> =25°C | 25      | Α  |
| PD                | Maximum Power Dissipation            | T <sub>C</sub> =25°C | 1.5     |    |
|                   |                                      | T <sub>C</sub> =70°C | 1       |    |
| $T_{J_i} T_{STG}$ | Junction & Storage Temperature Range |                      | -55~150 | °C |

## **Thermal Characteristics**

| Symbol | Parameter                              | Typical | Unit |
|--------|--|---------|------|
| Rθja   | Thermal Resistance-Junction to Ambient | 84      | °C/W |

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Electrical Characteristics (TA=25°C unless otherwise noted)

| Parameter                        | Test Conditions  | Min.   | Тур  | Max.  | Unit  |  |  |  |
|----------------------------------|--|--|--|---|---|--|--|--|
| Static Characteristics           |  |  |  |   |   |  |  |  |
| Drain-Source Breakdown Voltage   | $V_{GS}$ =0V, $I_D$ =250uA   | 20   | _  | _   | V   |  |  |  |
| Zero Gate Voltage Drain Current  | V <sub>DS</sub> =16V,V <sub>GS</sub> =0V   | _  |  | 1   | uA  |  |  |  |
|                                  | T <sub>J</sub> =55°C   | _  |  | 5   |   |  |  |  |
| Gate Threshold Voltage           | V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250uA  | 0.4  | 0.6  | 1   | V   |  |  |  |
| Gate Leakage Current             | V <sub>GS</sub> =±8V, V <sub>DS</sub> =0V  | _  | _  | ±10   | uA  |  |  |  |
| Drain-Source On-Resistance       | $V_{GS}$ =4.5V, $I_D$ =7A  |  | 16   | 20  | mΩ  |  |  |  |
|                                  | $V_{GS}$ =2.5V, $I_{D}$ =5.5A  | _  | 18   | 24  |   |  |  |  |
|                                  | $V_{GS}$ =1.8V, $I_D$ =5A  |  | 24   | 32  |   |  |  |  |
| Diode Characteristics            |  |  |  |   |   |  |  |  |
| Diode Forward Voltage            | I <sub>SD</sub> =1A,V <sub>GS</sub> =0V  | _  | 0.74   | 1.1   | V   |  |  |  |
| Diode Continuous Forward Current |  |  |  | 2   | Α   |  |  |  |
| Characteristics <sup>2</sup>     |  |  |  |   |   |  |  |  |
| Input Capacitance                | -V <sub>GS</sub> =0V, V <sub>DS</sub> =10V<br>-Frequency=1MHz  | _  | 1030   |   |   |  |  |  |
| Output Capacitance               |  | _  | 175  |   | pF  |  |  |  |
| Reverse Transfer Capacitance     |  | _  | 126  |   |   |  |  |  |
| Turn-On Delay Time               | $V_{DD}$ =10V, $I_{D}$ =6A,<br>$V_{GS}$ =4.5VR <sub>G</sub> =6 $\Omega$  | _  | 7  |   |   |  |  |  |
| Turn-On Rise Time                |  | _  | 13   |   | ns  |  |  |  |
| Turn-Off Delay Time              |  | _  | 53   |   |   |  |  |  |
| Turn-Off Fall Time               |  | _  | 15   |   |   |  |  |  |
| e Characteristics <sup>2</sup>   |  |  |  |   |   |  |  |  |
| Total Gate Charg                 | -V <sub>DS</sub> =10V,V <sub>GS</sub> =4.5V<br>-I <sub>D</sub> =6A   |  | 14   |   |   |  |  |  |
| Gate-to-Source Charge            |  | _  | 3  | -   | nC  |  |  |  |
| Gate-to-Drain Charge             |  |  | 4  |   |   |  |  |  |
|                                  | Drain-Source Breakdown Voltage  Zero Gate Voltage Drain Current  Gate Threshold Voltage  Gate Leakage Current  Drain-Source On-Resistance  Practeristics  Diode Forward Voltage  Diode Continuous Forward Current  Characteristics  Input Capacitance  Output Capacitance  Reverse Transfer Capacitance  Turn-On Delay Time  Turn-Off Delay Time  Turn-Off Fall Time  Characteristics  Total Gate Charg  Gate-to-Source Charge | $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$ | $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$ | $\begin{array}{c ccccccccccccccccccccccccccccccccccc$ | $\begin{array}{c ccccccccccccccccccccccccccccccccccc$ |  |  |  |

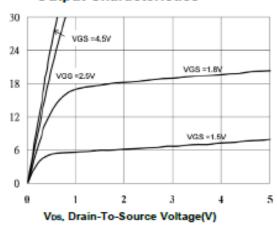
Note: 1: Pulse test; pulse width  $\leq$  300ns, duty cycle  $\leq$  2%.

<sup>2:</sup> Guaranteed by design, not subject to production testing.

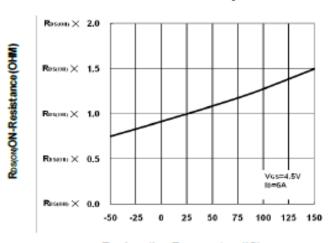
lp, Drain-To-Source Current(A)

## **Typical Operating Characteristics**

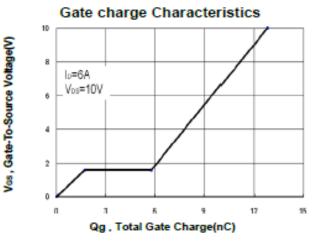




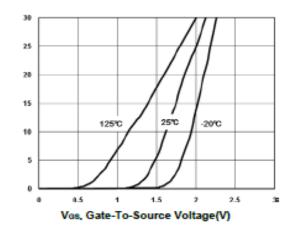
### On-Resistance VS Temperature



TJ, Junction Temperature(°C)

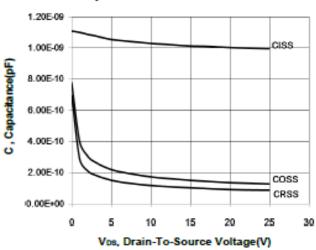


Transfer Characteristics

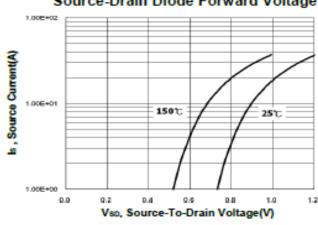


lo, Drain-To-Source Current(A)

#### Capacitance Characteristic



#### Source-Drain Diode Forward Voltage



SkySilicon

## **Typical Operating Characteristics**

